

PATENT APPLICATION

**RESPONSE UNDER 37 CFR §1.116
EXPEDITED PROCEDURE
TECHNOLOGY CENTER ART UNIT 2882**

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Akihiro MURATA

Group Art Unit: 2882

Application No.: 09/834,614

Examiner: G. WANG

Filed: April 16, 2001

Docket No.: 109278

For: THREE-DIMENSIONAL MOUNTED ASSEMBLY AND OPTICAL TRANSMISSION
DEVICE (AS AMENDED)

**SUPPLEMENTAL REQUEST FOR RECONSIDERATION
AFTER FINAL REJECTION**

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Further to the July 31, 2003 Request for Reconsideration After Final Rejection,
reconsideration based on the following comments is respectfully requested.

Claims 1-12 and 17-21 are pending. Claims 1-10 are withdrawn from consideration.

I. The Claims Define Allowable Subject Matter

The Office Action rejects claims 11-12 and 17-21 under 35 U.S.C. §103(a) as
unpatentable over U.S. Patent No. 5,522,002 to Chun in view of U.S. Patent No. 5,337,388 to
Jacobowitz et al. This rejection is respectfully traversed.

Neither Chun nor Jacobowitz, nor their combination, teach, disclose or suggest the
interconnections having a first exposed surface level with a first side of the molded body
wherein the interconnections have a second exposed surface level with a second side of the

RECEIVED
SEP - 3 2003
TECHNOLOGY CENTER 2800

molded body differing from the first side, as claimed in claim 11. Additionally, the applied art does not disclose an interconnection having an exposed surface formed by a mold by which a side of a molded body is formed, as claimed in claim 21.

The Examiner asserts that Figure 2, reference 216 is the molded body of Chun and is exposed on many sides. Further, the interconnection (reference 250) is connected on an exposed surface level to that of the molded body in that area of the molded body. An interconnection (reference 223) is connected on an exposed surface level to that of the molded body in that area of the molded body. Applicant respectfully disagrees with the Examiner's position.

Specifically, Figure 2 of Chun is an enlarged simplified perspective view of an optical interconnect module, with a portion thereof removed (as shown by the cross-hatching). Reference 250 is a wire bond which allows the lead frame member 211 to be operably connected to the plurality of electrical traces 203. This connection enables input and output of electrical signals to enter and to exit the inner workings of the interconnect module 201 through electrical leads 210. Additionally, reference 223 is a wire bond used to illustrate interconnection between contacts 205 and interconnect substrate 202.

According to the features recited in claim 11, the interconnections have a first exposed surface. This exposed surface is on the same plane as or level with a first side of the molded body. Further, the interconnections have a second exposed surface which is also on a same plane as, or in level with a second side of the molded body. The second side differs from the first side. Having the interconnections on the same plane as or level with their respective sides, provides the advantage of easily establishing the electrical connections on multiple sides of the molded body. The applied art does not teach, disclose or even suggest the above discussed features. Nor does the applied art provide the advantages as discussed above with respect to the claimed features.

As such, the applied art does not teach, disclose or even suggest having the interconnections with a first exposed surface level with a first side of the molded body and the interconnections having a second exposed surface level with a second side of the molded body differing from the first side, as claimed in claim 11.

Again, Figure 2 of Chun illustrates a cross-sectional view of the molded body and the interconnections so that their cross-sections are level. However, Chun fails to disclose that an exposed surface of the molded body and a side of the interconnections are level.

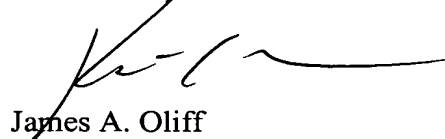
Therefore, Applicant submits for at least the reasons discussed above, independent claims 11 and 21 define patentable subject matter. Further, the claims that depend from the independent claims are distinguishable over the applied art for at least the reasons discussed, as well as for the additional features they recite. Withdrawal of the rejection of the claims under 35 U.S.C. §103 is respectfully requested.

II. Conclusion

In view of the foregoing, it is respectfully submitted that this application is in condition for allowance. Favorable reconsideration and prompt allowance are earnestly solicited.

Should the Examiner believe that anything further would be desirable in order to place this application in even better condition for allowance, the Examiner is invited to contact the undersigned at the telephone number listed below.

Respectfully submitted,



James A. Oliff
Registration No. 27,075

Kevin M. McKinley
Registration No. 43,794

JAO:KMM/jfl

Attachment:
Petition for Extension of Time

Date: September 3, 2003

OLIFF & BERRIDGE, PLC
P.O. Box 19928
Alexandria, Virginia 22320
Telephone: (703) 836-6400

<p>DEPOSIT ACCOUNT USE AUTHORIZATION Please grant any extension necessary for entry; Charge any fee due to our Deposit Account No. 15-0461</p>
--